



Huawei Ascend 310

Da Vinci SoC 2018 12nm

OVERVIEW

— FP32 TFLOPS	— VRAM LPDDR4X	— Memory Bandwidth	8 W TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
INT8	16.0	8	Standard
FP16	8.0	16	Standard

MEMORY SPECIFICATIONS

Capacity	—
Type	LPDDR4X
Bandwidth	—
Interface Width	128-bit

POWER & EFFICIENCY

TDP	8 W
Max Power	8 W
FP32 Efficiency	—
FP16 Efficiency	1.00 TFLOPS/W

HARDWARE DETAILS

Vendor: Huawei	Architecture: Da Vinci	Process Node: 12nm
Form Factor: SoC	Launch Year: 2018	

COMPUTE ENGINE

Da Vinci AI Core: 2

INTERCONNECT

PCIe: 3.0 x4

CHIP DESIGN

Die Size: 104 mm²